

# PVDF



## POLYVINYLIDENE FLUORIDE

### Material description

PVDF is a semi-crystalline thermoplastic and belongs to the group of fluoroplastics. In addition to its excellent chemical resistance, which is comparable with PTFE, PVDF has improved mechanical values (compared with PTFE). PVDF can be used over a wide temperature range (-50 °C to 150 °C) without loss of mechanical properties.

### Conformities

RoHS, REACH

Physical properties	Test method	Value	Unit
Density	DIN EN ISO 1183-1	1.78	g/cm <sup>3</sup>
Water absorption	DIN EN ISO 62	0.04	%
Sliding friction			
Abrasion resistance			

Mechanical properties	Test method	Value	Unit
Yield stress	DIN EN ISO 527	55	MPa
Elongation at break	DIN EN ISO 527	30	%
Tensile modulus of elasticity	DIN EN ISO 527	2100	MPa
Notched impact strength	DIN EN ISO 527	120	kJ/m <sup>2</sup>
Ball indentation hardness	DIN EN ISO 2039-1	130	MPa

Thermal properties	Test method	Value	Unit
Thermal conductivity	DIN 52612-2	0.2	W/(m*K)
Heat capacity	DIN 52612-1	1.2	kJ/(kg*K)
Coefficient of thermal expansion	DIN 53752	140	10 <sup>-6</sup> *K <sup>-1</sup>
Operating temperature short term		150	°C
Operating temperature long term		-20 bis 140	°C
Heat deflection temperature	DIN EN ISO 75 / A	115	°C
Flammability	UL 94, 3 mm	V0	

Electrical properties	Test method	Value	Unit
Volume resistivity	IEC 60093	10 <sup>14</sup>	Ω * cm
Surface resistivity	IEC 60093	10 <sup>14</sup>	Ω * cm
Dielectric strength	IEC 60243	21	kV/mm
Comparative tracking index (CTI)	IEC 60112	600	CTI

These technical data have been determined as average values by our suppliers from many individual measurements. In all measurements, the test specimens were tested in the dry state. We pass on the data with reservation. The table does not claim to be complete or correct. Material technology is subject to constant further development. No rights or guarantees can be derived from it. Own tests are necessary because the environmental and operating conditions (humidity, temperature, mechanical forces, radiation and chemicals, etc.) set limits in the application.